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ESD

TV

TSS

MOV

GDT

PIFD

DTC143XXX-MS

Product specification





Digital Transistors (Built-in Resistors)

FEATURES

- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors(see equivalent circuit)
- The bias resistors consist of thin-film resistors with complete isolation to allow negative biasing of the input. They also have the advantage of almost completely eliminating parasitic effects
- Only the on/off conditions need to be set for operation, making device design easy

Reference News

DTC143ZE-MS	MARKING
SOT-523	E23

DTC143ZE-MS	MARKING	
SOT-523	E23	

DTC143ZUA-MS	MARKING
3 SOT-323	E23

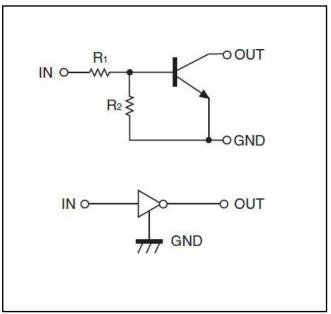
DTC143ZKA-MS	MARKING
3 SOT-23-3L	E23

DTC143ZCA-MS	MARKING
SOT-23	E23

PINNING

PIN	DESCRIPTION
1	IN
2	GND
3	OUT

Equivalent Circu





ORDERING INFORMATION

Orderable Device	Package	Packing Option
DTC143ZE-MS	SOT-523	3000PCS
DTC143ZUA-MS	SOT-323	3000PCS
DTC143ZKA-MS	SOT-23-3L	3000PCS
DTC143ZCA-MS	SOT-23	3000PCS

MAXIMUM RATINGS(Ta=25°C unless otherwise noted)

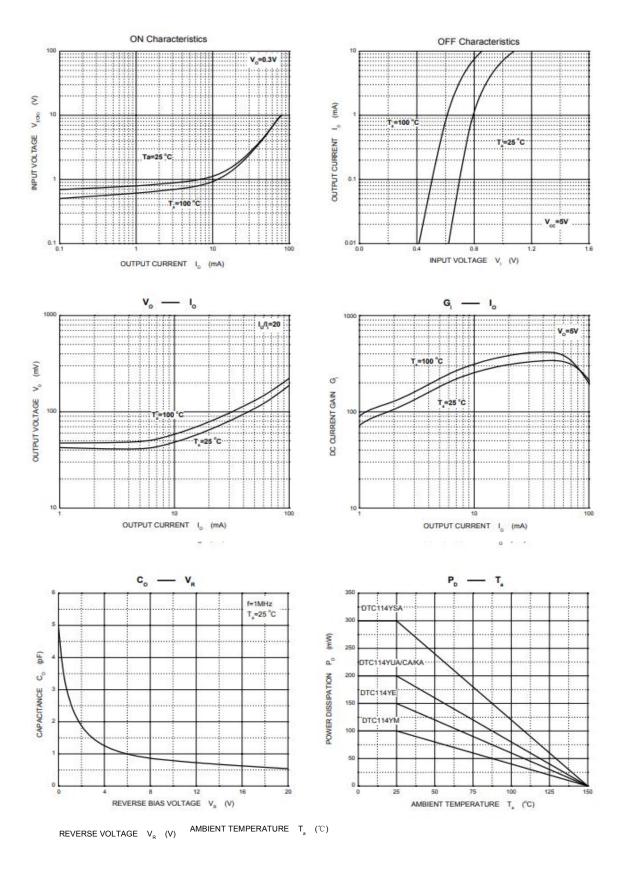
Symbol	Parameter	Limits(DTC143XXX-MS)			S)	Unit
Symbol	Farameter	E	UA	KA	CA	Ullit
V cc	Supply Voltage	50			V	
Vin	Input Voltage	- 5∼ + 30			V	
lo	Output Current	100			mA	
PD	Power Dissipation	150	200	200	200	mW
TJ,Tstg	Operation Junction and Storage Temperature Range	-55∼+150		$^{\circ}$		

ELECTRICAL CHARACTERISTICS (Ta=25[°]C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Input voltage	VI(off)	Vcc=5V,lo=100μA	0.5			V
input voitage	V _I (on)	Vo=0.3V ,lo=5mA			1.3	V
Output voltage	V _{O(on)}	lo/l _I =5mA/0.25mA		0.1	0.3	V
Input current	lı	V _I =5V			1.8	mA
Output current	IO(off)	Vcc=50V,Vi=0			0.5	μA
DC current gain	Gı	Vo=5V,lo=10mA	80			
Input resistance	R ₁		3.29	4.7	6.11	kΩ
Resistance ratio	R2/R1		8	10	12	
Transition frequency	f⊤	Vo=10V ,lo=5mA,f=100MHz		250		MHz

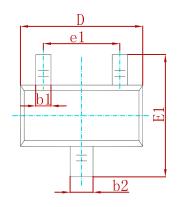


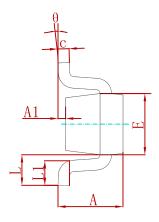
TypicalCharacteristics

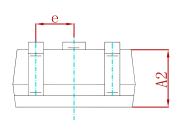




PACKAGE MECHANICAL DATA(SOT-523)

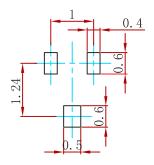






Symbol	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	0.700	0.900	0.028	0.035
A1	0.000	0.100	0.000	0.004
A2	0.700	0.800	0.028	0.031
b1	0.150	0.250	0.006	0.010
b2	0.250	0.350	0.010	0.014
С	0.100	0.200	0.004	0.008
D	1.500	1.700	0.059	0.067
E	0.700	0.900	0.028	0.035
E1	1.450	1.750	0.057	0.069
е	0.500	TYP.	0.020	TYP.
e1	0.900	1.100	0.035	0.043
L	0.400 REF.		0.016	REF.
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Suggested Pad Layout

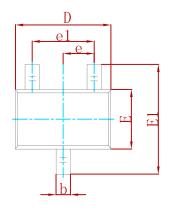


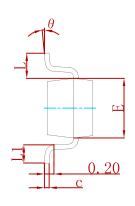
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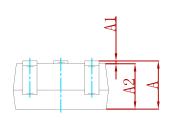
- 1.Controlling dimension:in millimeters. 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.



PACKAGE MECHANICAL DATA(SOT-323)

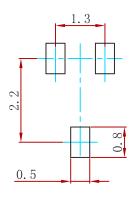






Symbol	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min	Max	Min	Max
Α	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
С	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
е	0.650) TYP	0.026	6 TYP
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021	I REF
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Suggested Pad Layout

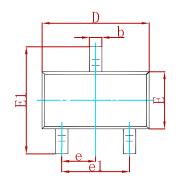


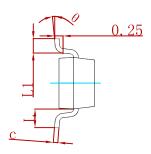
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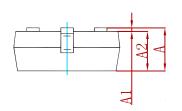
- 1. Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.



PACKAGE MECHANICAL DATA(SOT-23)

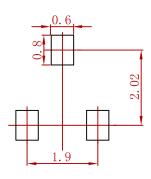






Cumbal	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min	Max	Min	Max
Α	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950) TYP	0.037	7 TYP
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022	REF
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout

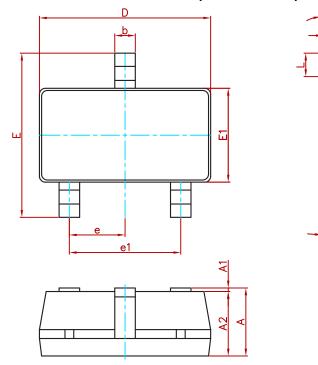


- Note:
 1.Controlling dimension:in millimeters.
 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

0.200

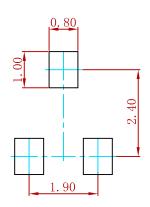


PACKAGE MECHANICAL DATA(SOT-23-3L)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
Е	2.650	2.950	0.104	0.116
е	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.



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